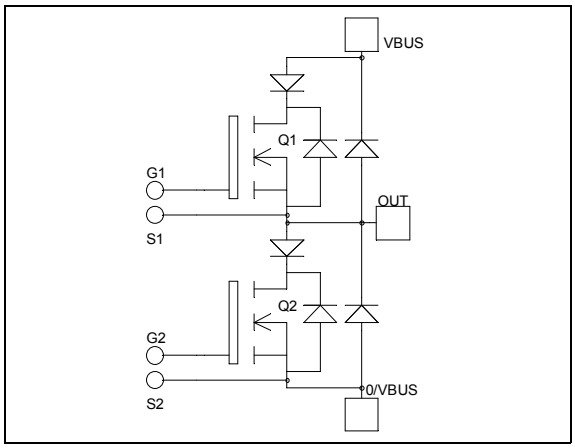
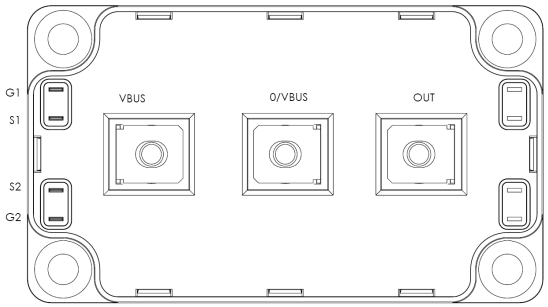
APTC80AM75SCG

Phase leg Series & SiC parallel diodes
Super Junction MOSFET Power Module

V_{DSS} = 800V
R_{DSon} = 75mΩ max @ Tj = 25°C
I_D = 56A @ Tc = 25°C





Application

- Motor control
- Switched Mode Power Supplies
- Uninterruptible Power Supplies

Features

- ***CoolMOS™***
  - Ultra low R_{DSon}
  - Low Miller capacitance
  - Ultra low gate charge
  - Avalanche energy rated
- ***Parallel SiC Schottky Diode***
  - Zero reverse recovery
  - Zero forward recovery
  - Temperature Independent switching behavior
  - Positive temperature coefficient on VF
- Kelvin source for easy drive
- Very low stray inductance
  - Symmetrical design
  - M5 power connectors
- High level of integration

Benefits

- Outstanding performance at high frequency operation
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Low profile
- RoHS Compliant

All ratings @ T_j = 25°C unless otherwise specified

Absolute maximum ratings

Symbol	*Parameter*		*Max ratings*	*Unit*
V_{DSS}	Drain - Source Breakdown Voltage		800	V
I_D	Continuous Drain Current	T_c = 25°C	56	A
		T_c = 80°C	43	
I_{DM}	Pulsed Drain current		232	
V_{GS}	Gate - Source Voltage		±30	V
R_{DSon}	Drain - Source ON Resistance		75	mΩ
P_D	Maximum Power Dissipation	T_c = 25°C	568	W
I_{AR}	Avalanche current (repetitive and non repetitive)		17	A
E_{AR}	Repetitive Avalanche Energy		0.5	mJ
E_{AS}	Single Pulse Avalanche Energy		670	

CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on www.microsemi.com

Electrical Characteristics

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
I_{DSS}	Zero Gate Voltage Drain Current	V_{GS} = 0V, V_{DS} = 800V	T_j = 25°C			100	µA
		V_{GS} = 0V, V_{DS} = 800V	T_j = 125°C			1000	
$R_{DS(on)}$	Drain – Source on Resistance	V_{GS} = 10V, I_D = 28A				75	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V_{GS} = V_{DS}, I_D = 4mA		2.1	3	3.9	V
I_{GSS}	Gate – Source Leakage Current	V_{GS} = ±20 V, V_{DS} = 0V				±200	nA

Dynamic Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
C_{iss}	Input Capacitance	V_{GS} = 0V V_{DS} = 25V f = 1MHz		9015		pF
C_{oss}	Output Capacitance			4183		
C_{rss}	Reverse Transfer Capacitance			215		
Q_g	Total gate Charge	V_{GS} = 10V V_{Bus} = 400V I_D = 56A		364		nC
Q_{gs}	Gate – Source Charge			48		
Q_{gd}	Gate – Drain Charge			184		
$T_{d(on)}$	Turn-on Delay Time	**Inductive switching @ 125°C** V_{GS} = 15V V_{Bus} = 533V I_D = 56A R_G = 1.2Ω		10		ns
T_r	Rise Time			13		
$T_{d(off)}$	Turn-off Delay Time			83		
T_f	Fall Time			35		
E_{on}	Turn-on Switching Energy	**Inductive switching @ 25°C** V_{GS} = 15V, V_{Bus} = 533V I_D = 56A, R_G = 1.2Ω		583		µJ
E_{off}	Turn-off Switching Energy			556		
E_{on}	Turn-on Switching Energy	**Inductive switching @ 125°C** V_{GS} = 15V, V_{Bus} = 533V I_D = 56A, R_G = 1.2Ω		1020		µJ
E_{off}	Turn-off Switching Energy			684		
R_{thJC}	Junction to Case Thermal Resistance				0.22	°C/W

Series diode ratings and characteristics

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
V_{RRM}	Maximum Peak Repetitive Reverse Voltage			1000			V
I_{RM}	Maximum Reverse Leakage Current	V_R=1000V				300	µA
I_F	DC Forward Current		T_c = 80°C		120		A
V_F	Diode Forward Voltage	I_F = 120A			1.9	2.5	V
		I_F = 240A			2.2		
		I_F = 120A	T_j = 125°C		1.7		
t_{rr}	Reverse Recovery Time	I_F = 120A V_R = 667V di/dt = 400A/µs	T_j = 25°C		280		ns
			T_j = 125°C		350		
Q_{rr}	Reverse Recovery Charge		T_j = 25°C		1.52		µC
			T_j = 125°C		7.2		
R_{thJC}	Junction to Case Thermal Resistance					0.46	°C/W

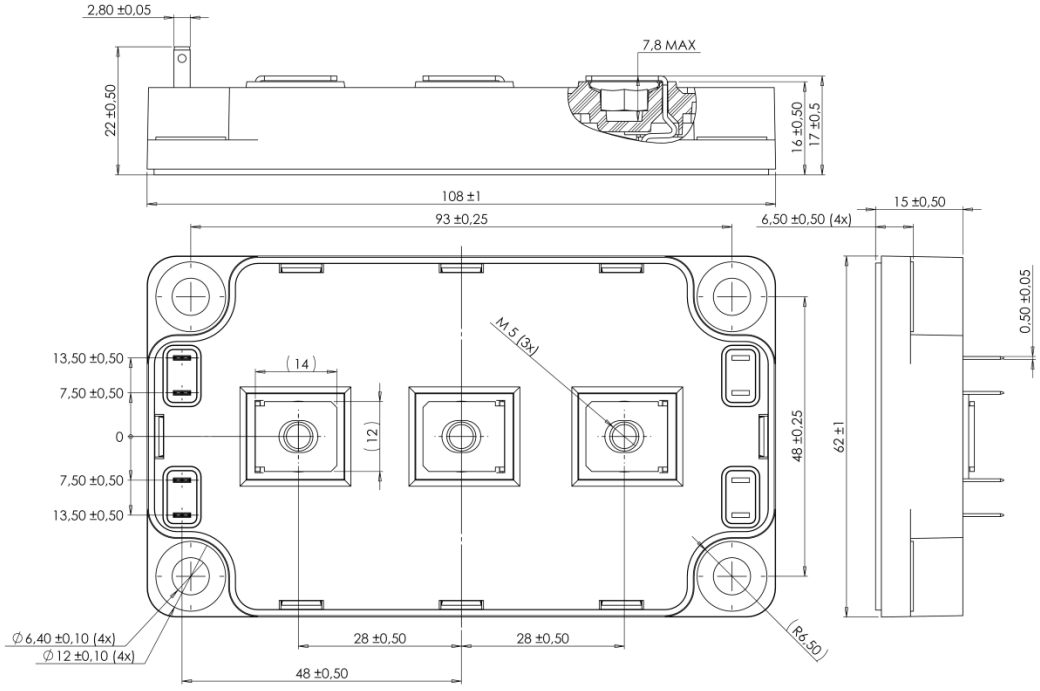
Parallel diode ratings and characteristics

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
V_{RRM}	Maximum Peak Repetitive Reverse Voltage			1200			V
I_{RM}	Maximum Reverse Leakage Current	V_R=1200V	T_j = 25°C		300	1200	µA
			T_j = 175°C		600	6000	
I_F	DC Forward Current		Tc = 100°C		30		A
V_F	Diode Forward Voltage	I_F = 30A	T_j = 25°C		1.6	1.8	V
			T_j = 175°C		2.6	3.0	
Q_C	Total Capacitive Charge	I_F = 30A, V_R = 1200V di/dt =1600A/µs			168		nC
Q	Total Capacitance	f = 1MHz, V_R = 200V			270		pF
		f = 1MHz, V_R = 400V			198		
R_{thJC}	Junction to Case Thermal Resistance					0.45	°C/W

Thermal and package characteristics

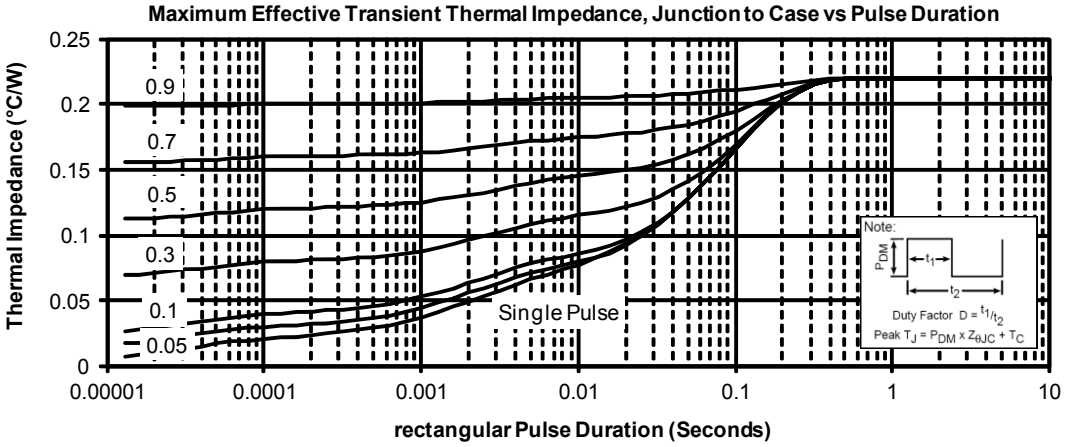
Symbol	Characteristic			Min	Max	Unit
V_{ISOL}	RMS Isolation Voltage, any terminal to case t =1 min, 50/60Hz			4000		V
T_J	Operating junction temperature range			-40	150	°C
T_{JOP}	Recommended junction temperature under switching conditions			-40	$T_J$max -25	
T_{STG}	Storage Temperature Range			-40	125	
T_C	Operating Case Temperature			-40	100	
Torque	Mounting torque	To heatsink	M6	3	5	N.m
		For terminals	M5	2	3.5	
Wt	Package Weight				300	g

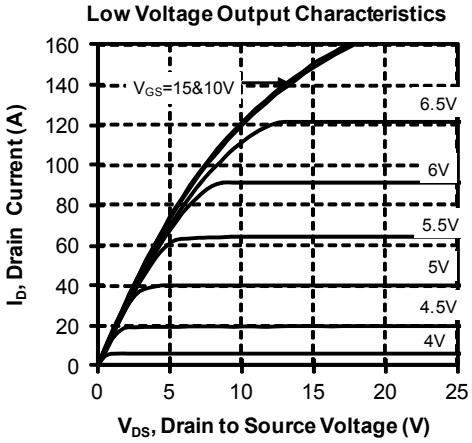
SP6 Package outline (dimensions in mm)

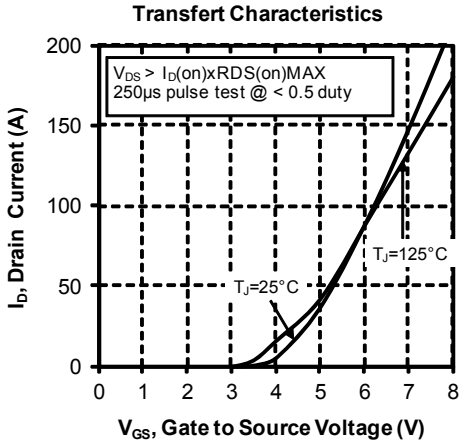


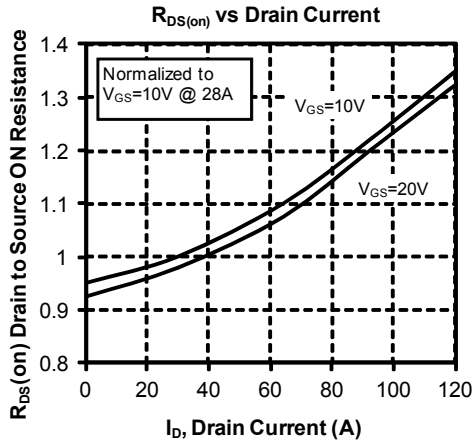
See application note APT0601 - Mounting Instructions for SP6 Power Modules on www.microsemi.com

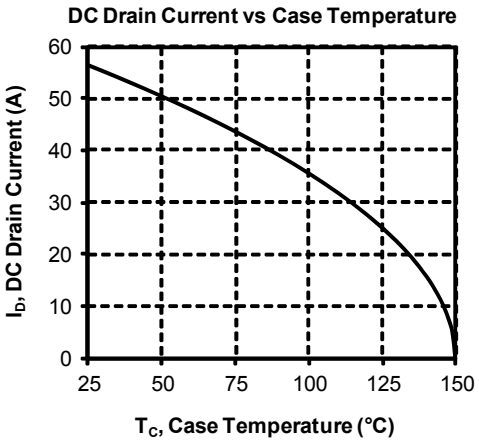
Typical CoolMOS Performance Curve



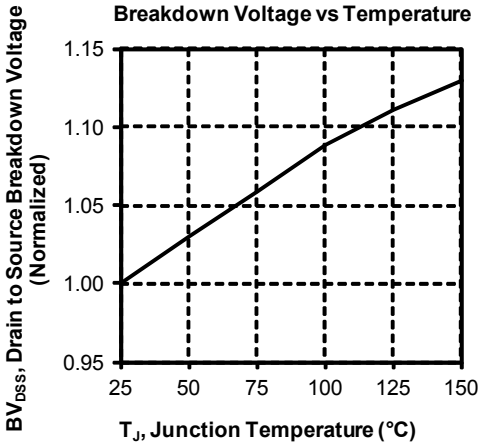




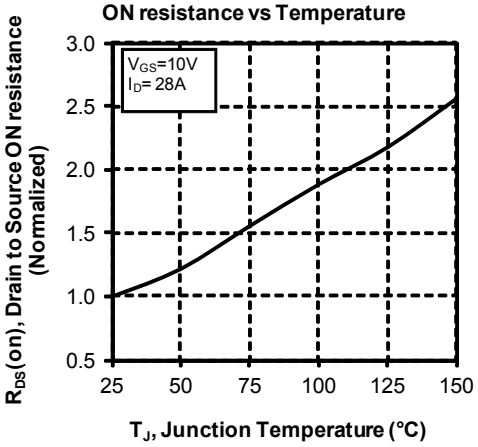




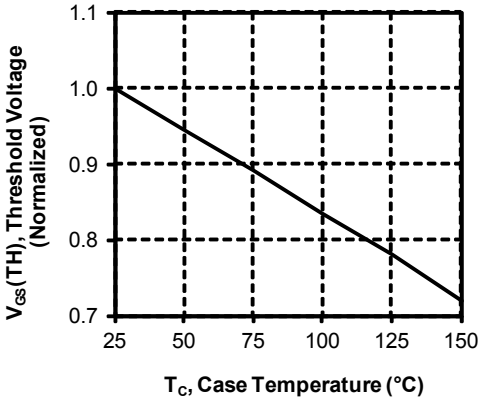
Breakdown Voltage vs Temperature



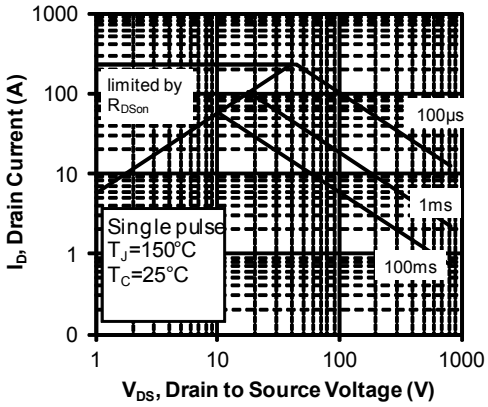
ON resistance vs Temperature



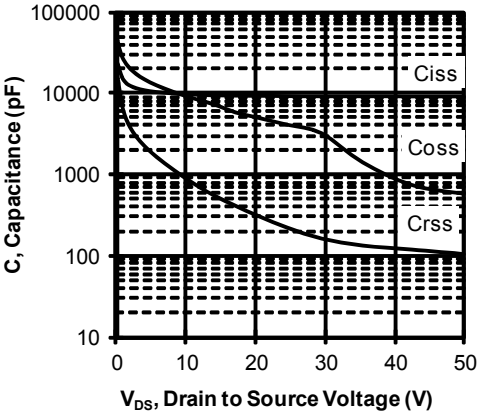
Threshold Voltage vs Temperature



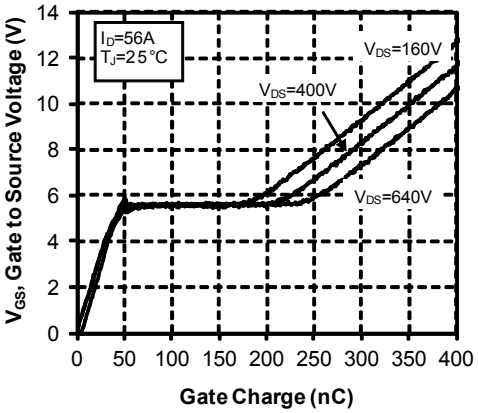
Maximum Safe Operating Area



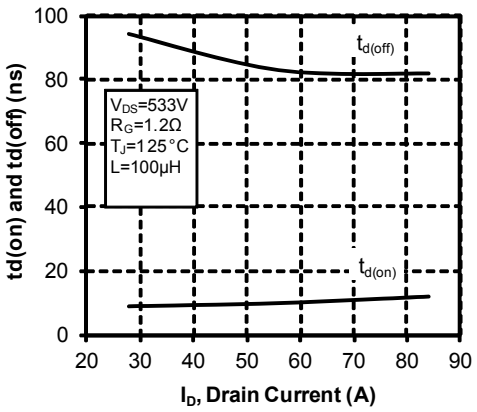
Capacitance vs Drain to Source Voltage



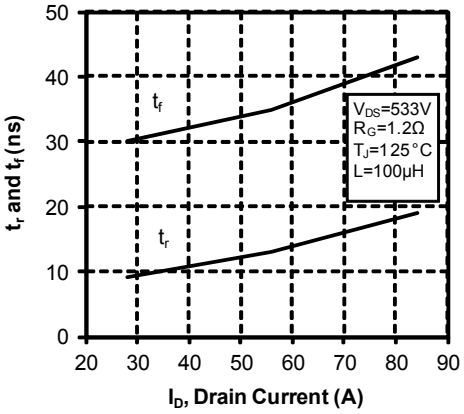
Gate Charge vs Gate to Source Voltage



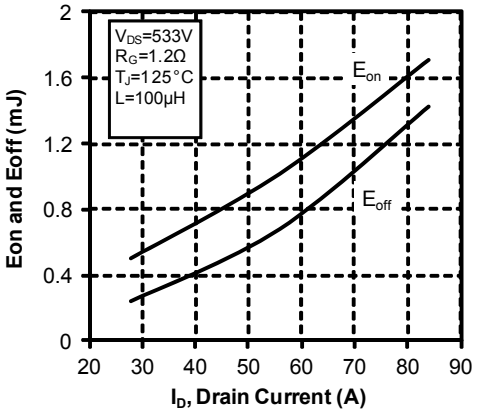
Delay Times vs Current



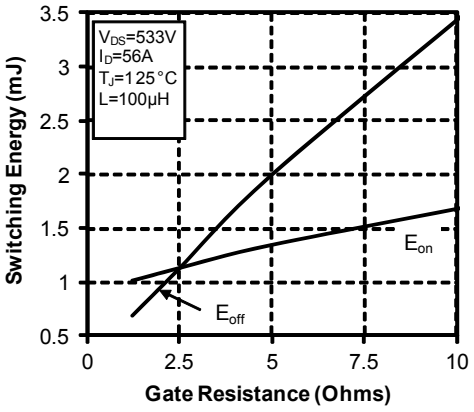
Rise and Fall times vs Current



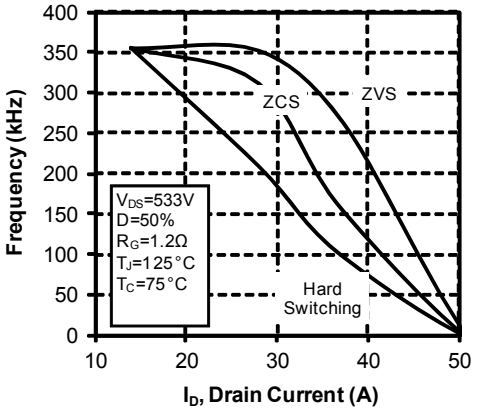
Switching Energy vs Current



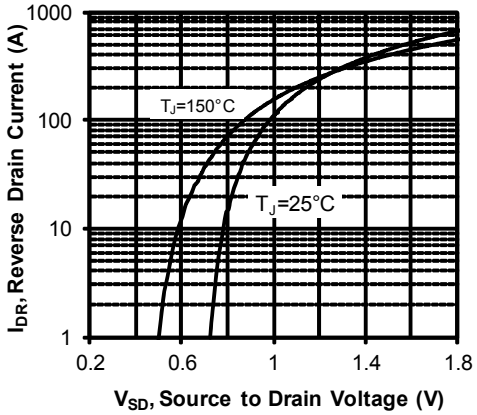
Switching Energy vs Gate Resistance



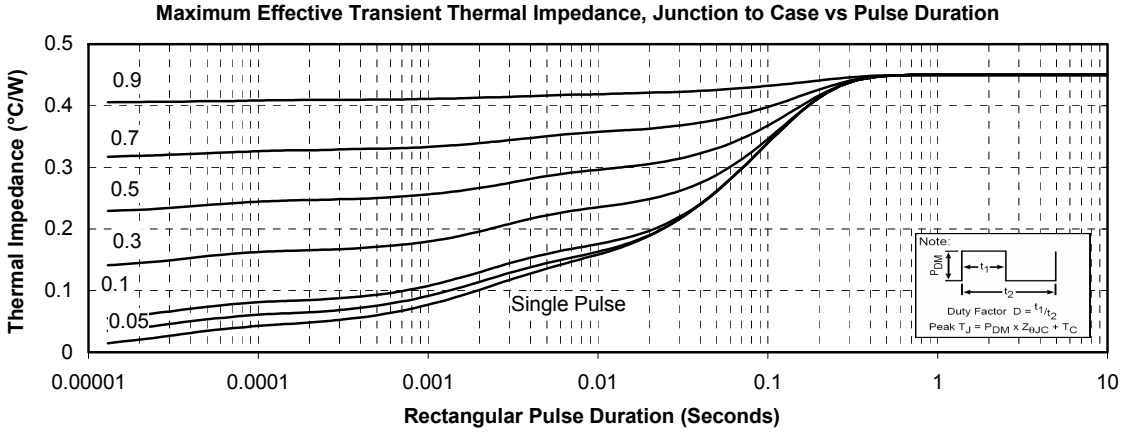
Operating Frequency vs Drain Current

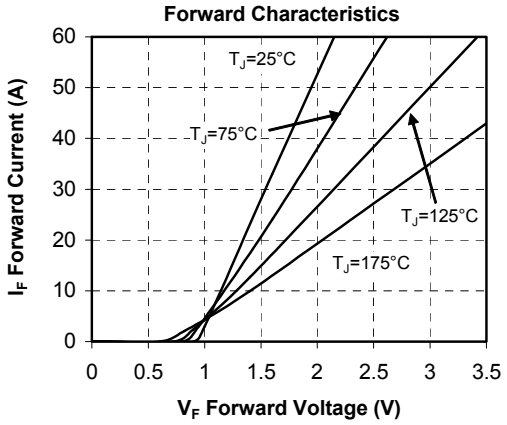


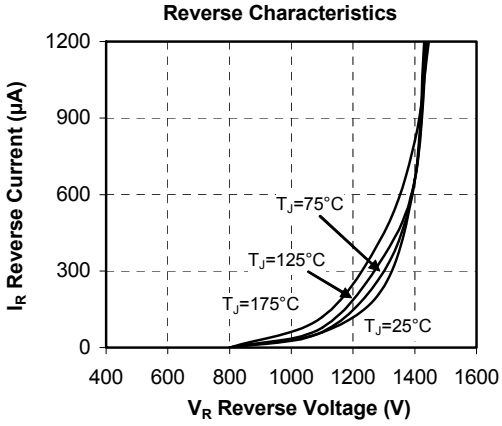
Source to Drain Diode Forward Voltage

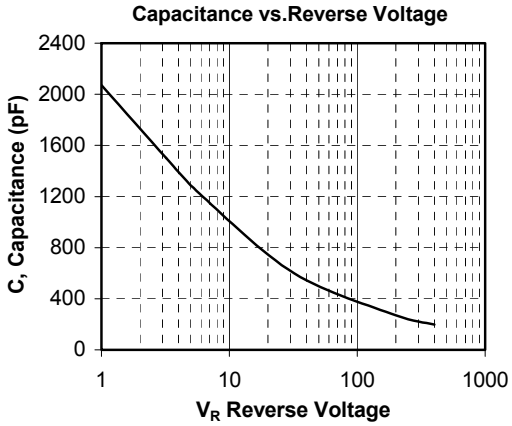


Typical SiC Diode Performance Curve









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